

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	457	(package or packaging or (chip or die or id) near2 (mounting)) and (warped or warping) near3 (board or substrate or pcb or pwb) and solder near3 (bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:22
L2	266	(mounting near board or wiring near board or pwb or pcb or interposer or (chip or die) near2 (mounting or carrier or holder or substrate)) and (deformation or deforming or deformed or deformable) near (board or substrate or pcb or pwb) and (cte or thermal near expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:23
L3	499	(mounting near board or wiring near board or pwb or pcb or interposer or (chip or die) near2 (mounting or carrier or holder or substrate)) and (deformation or deforming or deformed or deformable or warping or warpage) near4 (cte or thermal near expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:24
L4	160	(bga or ball adj grid adj array) near2 (warp or warpage or warping or warped or cte or thermal near expansion or thermally near2 expand\$3 or bending or bent)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:24
L5	70	438/457.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:34
L6	458	(wiring adj board or mounting adj board or circuit adj board or interposer or wiring near substrate or mounting near substrate) near6 (warped or warpage or warping or deformation or deforming or deformed or concave or curving or curved or convex) near5 (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:35
L7	63	(wiring adj board or mounting adj board or circuit adj board or interposer or wiring near substrate or mounting near substrate) near6 (warped or warpage or warping or deformation or deforming or deformed or concave or curving or curved or convex) near5 (multi or multiple or plural or plurality or two or several or second or both near sides or top near bottom) near3 (chip or die or ic or device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:38
L8	73	(wiring adj board or mounting adj board or circuit adj board or interposer or wiring near substrate or mounting near substrate) near5 (recess or recessed or groove or indent or indentation or concave or concavity) near4 (chip or die or ic or device) near4 (bottom or under or underneath or below)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:39
L9	0	(wiring adj board or mounting adj board or circuit adj board or interposer or wiring near substrate or mounting near substrate) near5 (recess or recessed or groove or indent or indentation or concave or concavity) near4 (chip or die or ic or device) near4 (bottom or under or underneath or below) near10 (warpage or warping or cte or thermal near expansion or deformation or deforming or bending or bent)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:40
L10	253	flip adj chip near4 (warping or warpage or warped or thermal near expansion or bending or curving or deforming or deformation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:42
L11	2	flip adj chip near4 (warping or warpage or warped or bending or curving or deforming or deformation) near6 (thermal near expansion or thermally near expanding or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/04 16:43